Bridge Rectifiers

RABS2J THRU RABS2M 600 to 1000 V 2.0 A

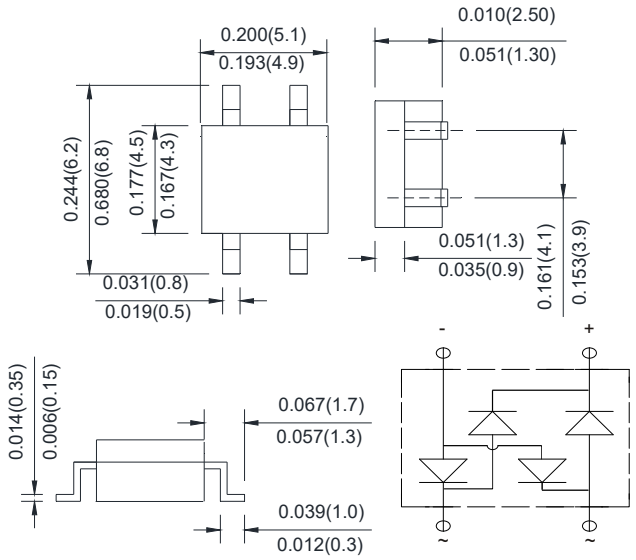
Typical Applications

General purpose use in AC/DC bridge full wave rectification for SMPS, lighting ballast, adapter, battery charger, home appliances, office equipment, and telecommunication applications.

Features And Mechanical Data

- Package:ABS
- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Glass passivated Junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed 250℃/10 seconds at terminals applications.
- Terminals: Tin plated leads, solderable per STD-002 and JESD22-B102
- Polarity: As marked on body

ABS



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Ratings at 25℃ ambient temperature unless otherwise specified. Single phase , half wave, 60HZ, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter / Type number marking code	Symbols	RABS26 RABS2J	RABS26 RABS2K	RABS210 RABS2M	Units
Maximum recurrent peak reverse voltage	VRRM	600	800	1000	Volts
Maximum rms voltage	VRMS	420	560	700	Volts
Maximum dc blocking voltage	VDC	600	800	1000	Volts
Maximum average forward rectified current. Lead length Sine wave 60Hz resistive or Inductive Load	I(AV)	2.0 (Fig. 1)			Amp
Peak forward surge current, 8.3 ms single half- sine-wave Superimposed on rated load (jedec method) (rating of per diode)	IFSM	60			Amp
Maximum instantaneous forward voltage drop per diode at 1/2 I(AV)	VF	1.0			Volts
Maximum DC reverse current at rated DC blocking voltage per	IR	5 500			uA
Current squared time @1ms≤t≤8.3ms Tj=25℃, Rating of per diode	I^2t	15			A2S
Max Reverse recovery time @IF= 0.5A, Irr=0.25A, IR=1.0A	Trr	350			nS
Typical thermal resistance between junction and ambient	RΘJA	70			℃/W
Typical thermal resistance between junction and case	RΘJC	30			℃/W
Typical thermal resistance between junction and lead	RΘJL	25			℃/W
Junction temperature	T_J	-65 to +150			℃
Storage temperature range	T_{STG}	-65 to +150			℃

Note:

1.Unit mounted on 13 mm*13 mm*1.6 mm 1oz/ft2 glass epoxy PCB board,pad per pin with 2*2mm solder pad areas
2.Thermal resistance junction to case, lead and ambient in accordance with JESD-51.
3.The typical data above is for reference only.

※**This product The above data sheet typical data meet the Mentioned standards,designers for reference only**

Ordering Information (Example)

Prefered P/N	Package code	Unit weight(g)	Minimum Package(pcs)	Inner box Quantity(pcs)	Outer carton quantity(pcs)	Delivery mode
ABS	F1	about 0.095	5000	10000	100000	13' reel

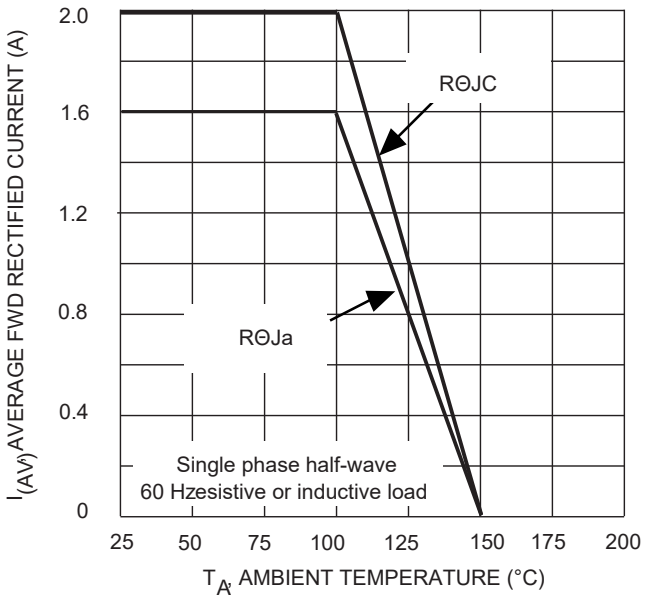


Fig. 1 Forward Derating Curve

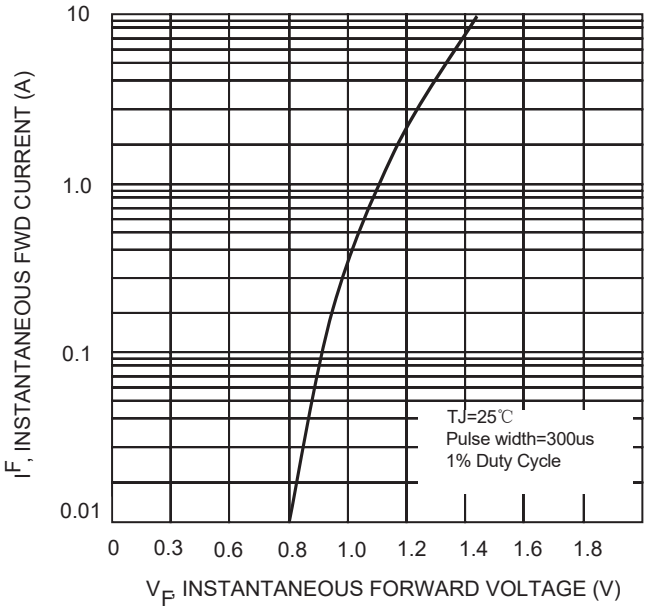


Fig. 2 Typical Forward Characteristics

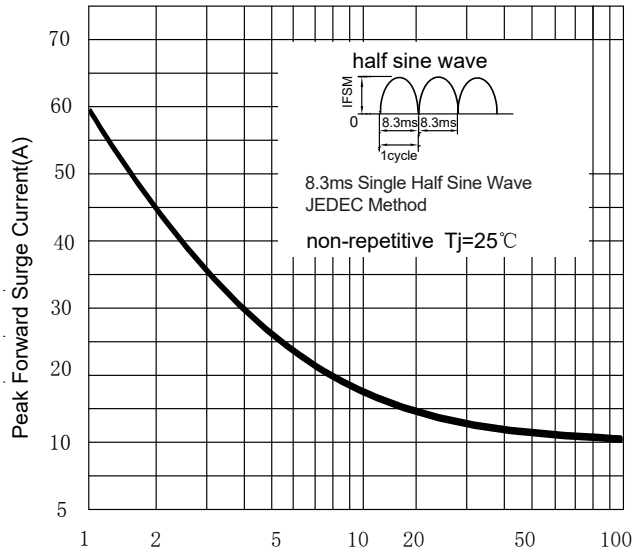


Fig. 3 Peak Forward Surge Current

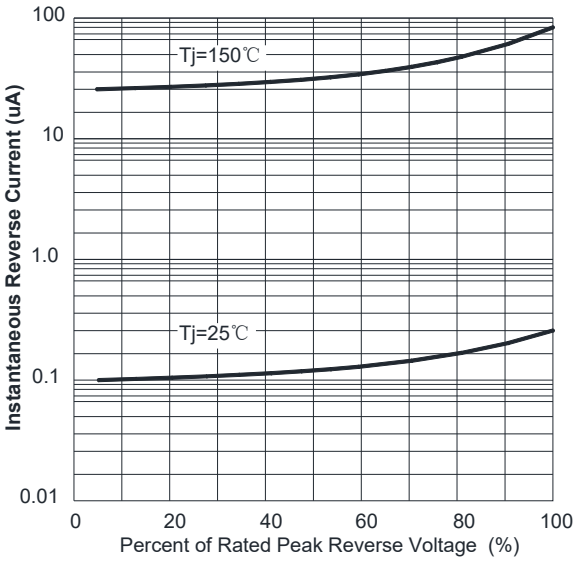


FIG4:Typical Reverse Characteristics